

Description

The MGD623N is 600 V trench IGBT. Sanken original trench structure decreases gate capacitance, and achieves high speed switching and switching loss reduction. Thus, the IGBT can improve the efficiency of your circuit.

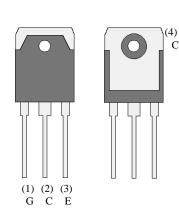
Features

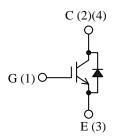
- Low Saturation Voltage
- High Speed Switching
- With Integrated Low V_F Fast Recovery Diode
- Bare Lead Frame: Pb-free (RoHS Compliant)

Applications

- Microwave Oven
- IH Cooker
- Inverter Circuit







Not to scale

Absolute Maximum Ratings

Parameter	Symbol	Conditions	Rating	Unit	Remarks
Collector to Emitter Voltage	V _{CE}		600	V	
Gate to Emitter Voltage	V _{GE}		±30	V	
Continuous Collector Current	I _C	$T_C = 25 \ ^{\circ}C$	50	А	
		$T_{\rm C} = 100 \ ^{\circ}{\rm C}$	37	А	
Pulsed Collector Current	I _{C(PULSE)}	$\begin{array}{l} P_W \leq 1 \text{ ms,} \\ \text{duty cycle} \leq 1\% \end{array}$	100	А	
Diode Continuous Forward Current	I _F	$T_C = 25 \ ^{\circ}C$	30	А	
Diode Pulsed Forward Current	I _{F(PULSE)}	$\begin{array}{l} P_W \leq 1 \text{ ms,} \\ \text{duty cycle} \leq 1\% \end{array}$	60	А	
Maximum Collector to Emitter dv/dt	dv/dt	$T_C \le 125 \text{ °C},$ see Figure 1	5	V/ns	
Power Dissipation	P _D	$T_C = 25 \ ^{\circ}C$	150	W	
Operating Junction Temperature	T _J		150	°C	
Storage Temperature	T _{STG}		-55 to 150	°C	

Unless otherwise specified, $T_{A} = 25 \ ^{\circ}C$.

Thermal Characteristics

Unless otherwise specified, $T_A = 25$ °C.

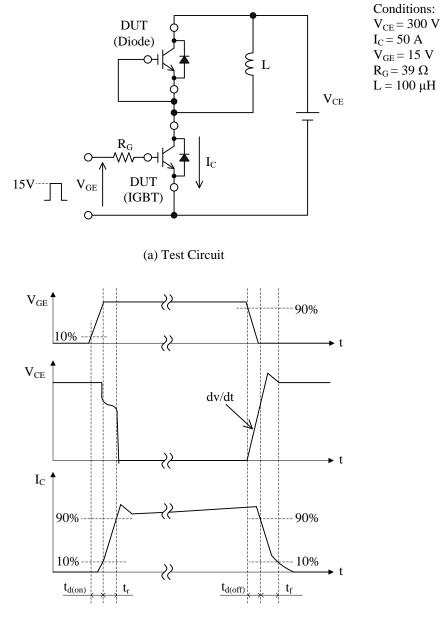
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	Remarks
Thermal Resistance of IGBT (Junction to Case)	$R_{\theta JC(IGBT)}$			_	0.833	°C/W	
Thermal Resistance of Diode (Junction to Case)	$R_{\theta JC(Di)}$				1.67	°C/W	

Electrical Characteristics

Unless	otherwise	specified.	$T_{A} = 25$	°C.
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Parameter Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector to Emitter Breakdown Voltage	V _{(BR)CES}	$I_{C} = 100 \ \mu A, V_{GE} = 0 \ V$	600			V
Collector to Emitter Leakage Current	I _{CES}	$V_{CE} = 600 \text{ V}, V_{GE} = 0 \text{ V}$	—		100	μΑ
Gate to Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30 \text{ V}$	_	_	±500	nA
Gate Threshold Voltage	V _{GE(TH)}	$V_{CE} = 10 \text{ V}, I_C = 1 \text{ mA}$	3	4.5	6	V
Collector to Emitter Saturation Voltage	V _{CE(sat)}	$V_{GE} = 15 \text{ V}, I_C = 50 \text{ A}$		1.7	2.3	V
Input Capacitance	C _{ies}	$V_{CE} = 20 V,$	—	2500	—	pF
Output Capacitance	C _{oes}	$V_{GE} = 0 V,$		150	_	
Reverse Transfer Capacitance	C _{res}	f = 1.0 MHz		80		
Total Gate Charge	Q_{G}	$V_{CE} = 300 V$ $I_{C} = 50 A$		65		nC
Gate to Emitter Charge	Q_{GE}			20		
Gate to Collector Charge	Q _{GC}	$V_{GE} = 15 V$		20		
Turn-on Delay Time	t _{d(on)}			75		ns
Rise Time	t _r	$T_J = 25 $ °C, see Figure 1		100		
Turn-off Delay Time	$t_{d(off)}$			300		
Fall Time	t _f			200		
Turn-on Delay Time	t _{d(on)}			75		ns
Rise Time	t _r	$T_J = 125 \ ^{\circ}C,$ see Figure 1		100		
Turn-off Delay Time	$t_{d(off)}$			300		
Fall Time	t _f	1		350		
Emitter to Collector Diode Forward Voltage	$V_{\rm F}$	$I_F = 30 \text{ A}$		1.2	1.6	V
Emitter to Collector Diode Reverse Recovery Time	t _{rr}	$ I_F = 30 \text{ A}, \\ di/dt = 100 \text{ A}/\mu s $		300		ns

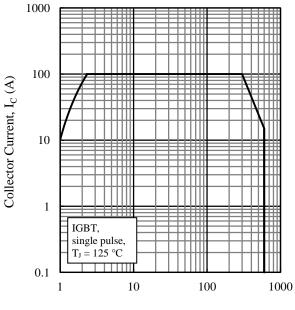
Test Circuits and Waveforms



(b) Waveform

Figure 1. Test Circuits and Waveforms of dv/dt and Switching Time

Rating and Characteristic Curves



Collector-Emitter Voltage, V_{CE} (V)

Figure 2. IGBT Reverse Bias Safe Operating Area

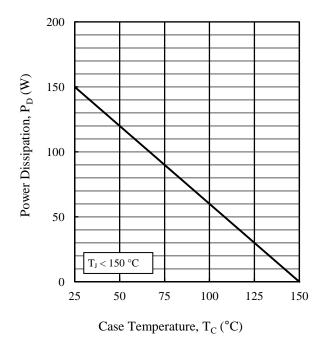


Figure 4. Power Dissipation vs. Case Temperature

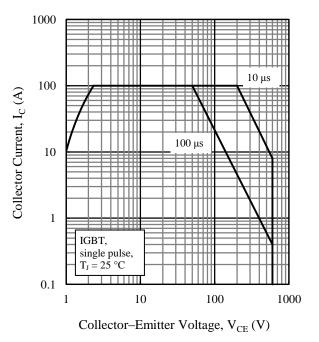


Figure 3. IGBT Safe Operating Area

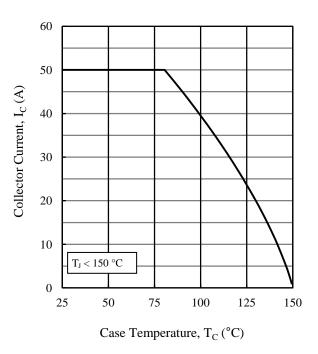


Figure 5. Collector Current vs. Case Temperature

MGD623N

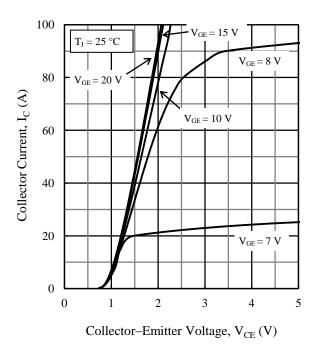


Figure 6. Output Characteristics ($T_J = 25 \ ^{\circ}C$)

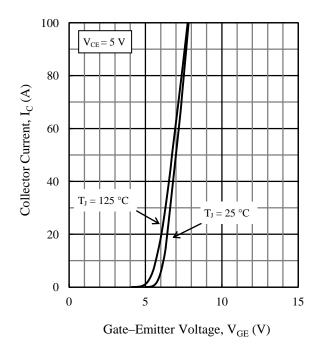


Figure 8. Transfer Characteristics

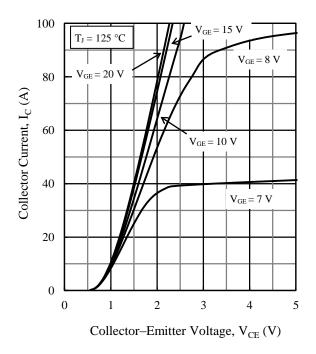


Figure 7. Output Characteristics ($T_J = 125 \ ^{\circ}C$)

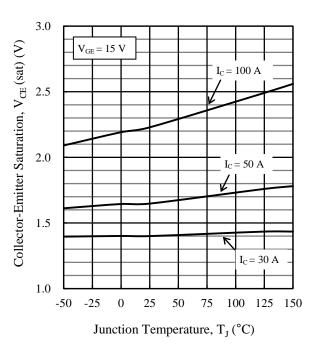


Figure 9. Saturation Voltage vs. Junction Temperature

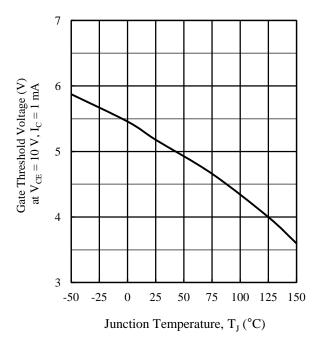


Figure 10. Gate Threshold Voltage vs. Junction Temperature

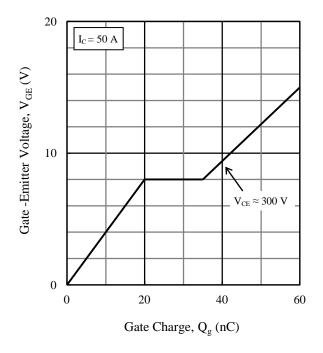


Figure 12. Typical Gate Charge

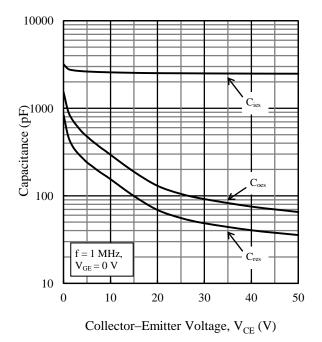


Figure 11. Capacitance Characteristics

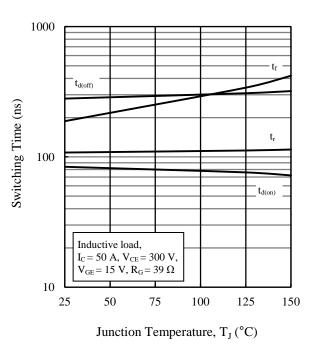


Figure 13. Switching Time vs. Junction Temperature

MGD623N

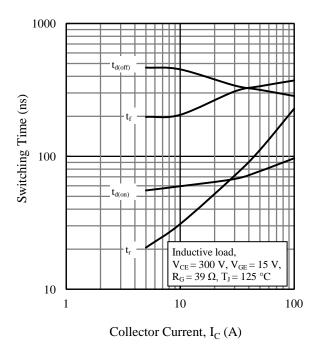


Figure 14. Switching Time vs. Collector Current

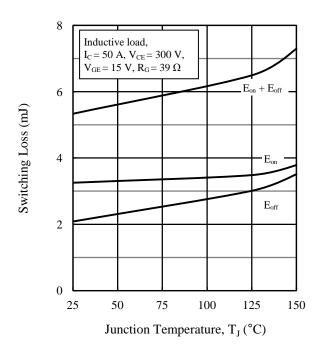
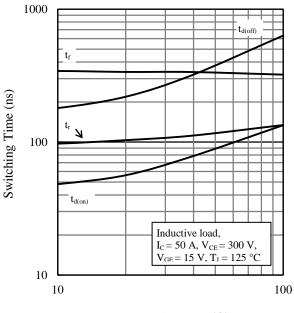


Figure 16. Switching Loss vs. Junction Temperature



Gate Resistor, $R_{G}(\Omega)$

Figure 15. Switching Time vs. Gate Resistor

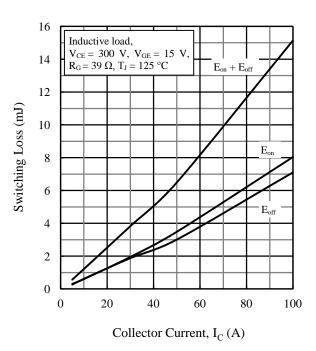


Figure 17. Switching Loss vs. Collector Current

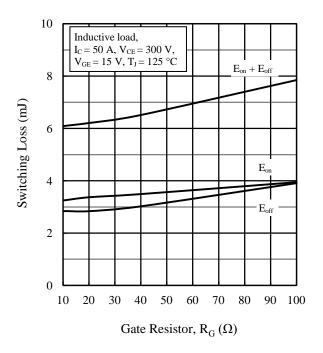


Figure 18. Switching Loss vs. Gate Resistor

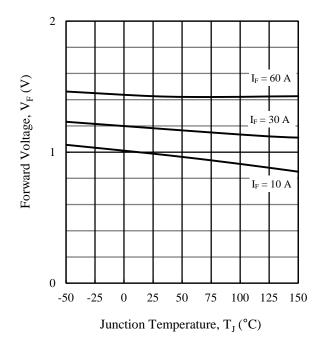


Figure 20. Diode Forward Voltage vs. Junction Temperature

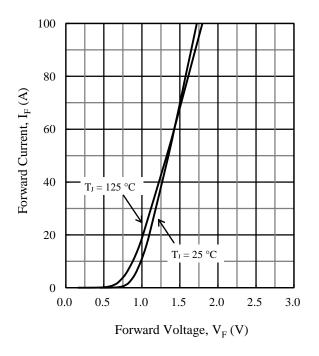


Figure 19. Diode Forward Characteristics

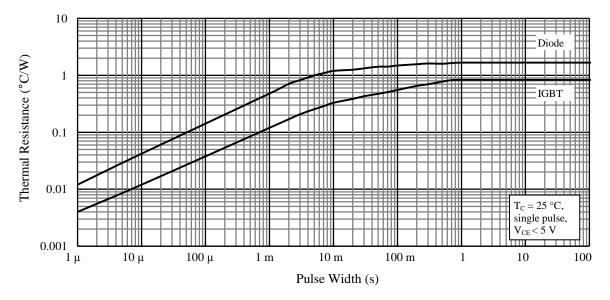
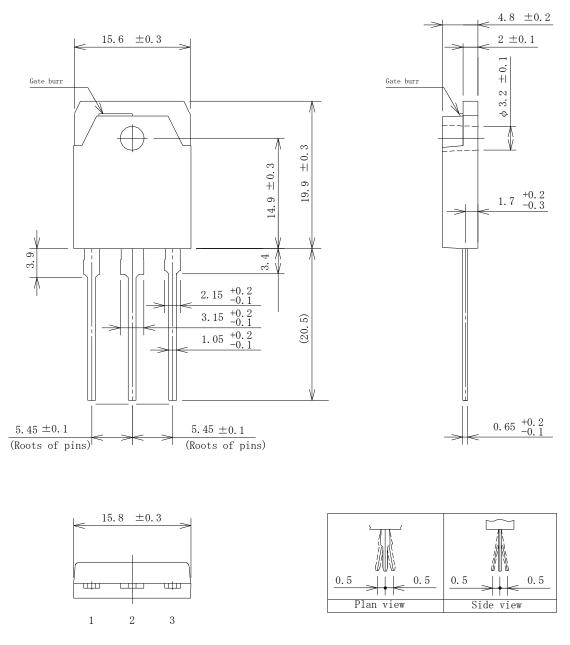


Figure 21. Transient Thermal Resistance

Physical Dimension

• TO3P-3L



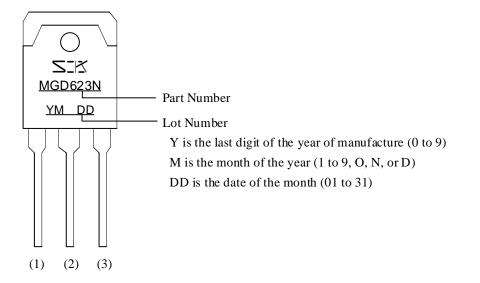
NOTES:

- Dimensions in millimeters
- Maximum gate burr height is 0.3 mm
- Bare lead frame: Pb-free (RoHS compliant)
- When soldering the products, be sure to minimize the working time within the following limits:

Flow: $260 \pm 5 \text{ °C} / 10 \pm 1 \text{ s}$, 2 times Soldering iron: $380 \pm 10 \text{ °C} / 3.5 \pm 0.5 \text{ s}$, 1 time (Soldering should be at a distance of at least 1.5 mm from the body of the product.)

- Recommended screw torque: 0.686 N·m to 0.882 N·m (7 kgf·cm to 9 kgf·cm)

Marking Diagram



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